



Patent

Customer No.: 31561  
Docket No.: 10546-US-PA  
Application No.: 10/709,953

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Huang et al.

Application No. : 10/709,953

Filed : 2004/6/9

For : CHIP PACKAGING STRUCTURE HAVING  
REDISTRIBUTION LAYER WITH RECESS

Art Unit : 2826

Examiner : Williams, Alexander O.

**TRANSMITTAL LETTER**

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(Via fax: 1+2 pages)

Assistant Commissioner for Patents  
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated April 4, 2007 transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Please charge the fee in the amount of \$1700.00 for Issue Fee and Publication Fee to Account No. 50-2620 (Order No.: 10546-US-PA).

Please be kindly advised that the title of the invention has been amended to "CHIP PACKAGING STRUCTURE HAVING REDISTRIBUTION LAYER WITH RECESS" in the amendment and response to office action, dated November 1, 2006.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: June 27, 2007

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